Amendments to the Specification:

In the Title:

Page 1, line 1, please replace the title with the following rewritten title:

--FILM CARRIER TAPE FOR MOUNTING AN ELECTRONIC PART--

Please replace the paragraph beginning on page 11, line 1, with the following rewritten paragraph:

-- As shown in Fig. 1, the insulating film 10 for constituting the film carrier tape for mounting an electronic part of the present invention is ~~bought~~ brought into contact with an acid or the like when subjected to etching and is heated when subjected to bonding, so that it has properties of being not damaged by such chemicals, namely, chemical resistance, and properties of being not deteriorated by such heat, namely, heat resistance. Examples of materials for forming the insulating film 10 include polyester, polyamide and polyimide. In the present invention, a film made of polyimide is preferably employed. The polyimide has prominent heat resistance as compared with other resins and is excellent also in the chemical resistance. --

Please replace the paragraph beginning on page 12, line 5, with the following rewritten paragraph:

-- In the ~~insulting~~ insulating film for constituting the film carrier tape for mounting an electronic part of the present invention, sprocket holes (perforations) are formed on its both side edges. Further, solder ball holes 11 where ball pads 18 are exposed, slits, alignment mark holes, etc. are formed. --

Please replace the paragraph beginning on page 12, line 11, with the following rewritten paragraph:

-- In the film carrier tape for mounting an electronic part of the present invention, a wiring pattern 12 is provided on the surface of the above-mentioned insulating film 10. The wiring pattern 12 is generally formed by selectively etching a conductive metal foil disposed on the surface of the ~~insulting~~ insulating film 10. For example, a conductive metal foil is stuck onto the surface of the ~~insulting~~ insulating

film 10 preferably through an adhesive layer 13, and on the conductive metal foil, a photosensitive resin layer is formed. Then, the photosensitive resin layer is subjected to light exposure and development to form a desired pattern, and the conductive metal is subjected to etching using the pattern as a masking material, whereby a desired wiring pattern 12 can be formed. Examples of the conductive metals employable herein include an aluminum foil and a copper foil. As the conductive metal foil, a metal foil having a thickness of usually 3 to 35 μm, preferably 9 to 25 μm, is employable. --

Please replace the paragraph beginning on page 23, line 17, with the following rewritten paragraph:

-- In order to obtain a good balance between the wire bonding properties on the surface of the bonding pad (connecting terminal) 17 and the adhesion properties of the solder ball 30 to the ball pad 18, the thickness of the ~~intermediated~~ intermediate layer 22 containing palladium as a main constituent needs to be extremely reduced, i.e., not more than 0.04 μm, as adopted in the present invention. For stably keeping adhesion strength of the solder ball 30 to the ball pad 18 with high values, it is very advantageous to set the thickness of the intermediate layer containing palladium as a main constituent in the aforesaid range and to thinly form the surface layer 23 containing gold as a main constituent. --

In the Abstract:

Please replace the Abstract on page 38 with the following rewritten Abstract. A clean copy of the Abstract is attached hereto on a separate page.

-- ~~Disclosed is a~~ A film carrier tape for mounting an electronic part comprising an insulating film and a wiring pattern which is made of a conductive metal and is provided on the surface of the insulating film, wherein an undercoating layer containing nickel as a main constituent is formed on at least a part of the surface of the wiring pattern made of a conductive metal, an intermediate layer containing palladium as a main constituent is formed on the surface of the undercoating layer, a surface layer containing gold as a main constituent is formed on the surface of the intermediate layer, and the average thickness of the intermediate layer containing

palladium as a main constituent is not more than 0.04 μm. ~~According to the present invention, a film carrier tape for mounting electronic part, in which the wire bonding strength to the bonding pad (connecting terminal) and the peel strength of the solder ball to the ball pad are high and the variability range of these strengths is small, is provided~~. --